











# PRODUCT DATASHEET



- ► PLCC2
- ► K1 Series
- ► Cool White (6300K)

NOW09S24 (Tube) NOW09S24RL (Reel)





**APPLICATIONS:** 

Flash Lighting

Reading Lights

**General Lighting** 

**Commercial Lighting** 

**Residential Lighting** 

**Architectural Lighting** 

# **K1 Series**





#### **FEATURES:**

Package: PLCC White SMT Package

Forward Current: 700mA Forward Voltage (typ.): 3.2V

Luminous Flux (typ.): 220lm @700mA

Colour: Cool White

**CCT:** 6300K

Viewing angle: 120°

**Materials:** 

Die: InGaN

Resin: Silicon (Water Clear)

Operating Temperature: -30~+100°C

Storage Temperature: -40~+120°C

**Grouping parameters:** 

- Forward voltage
- Luminous flux
- **CIE Chromaticity**
- Soldering methods: Reflow soldering
- Packing: 2000pcs/carton (40 tubes); 50pcs/tube

Preconditioning: acc. to JEDEC Level 3

24mm tape with 1000pcs/reel, ø330mm (13")



#### **CHARACTERISTICS:**

## Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I <sub>F</sub>	700	mA
Peak Forward Current Duty 1/10@10KHz	IFP	800	mA
Operating Temperature	T <sub>OPR</sub>	-30~+100	°C
Storage Temperature	T <sub>STG</sub>	-40~+120	°C
Junction Temperature	Tj	110	°C
Temperature Coefficient of VF	$\Delta V_F/\Delta T_j$	-2	mV/°C
Thermal Resistance Junction to Lead	T <sub>juction-lead</sub>	12	°C/W

<sup>1.</sup> Not suitable to be driven in reverse bias.

## Electrical & Optical Characteristics (Ta=25°C)

Darameter	Cumbal		Values	l loit	Test		
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition	
Forward Voltage	$V_{F}$	2.8	3.2	3.6	V	I <sub>F</sub> =700mA	
Luminous Flux	Ф۷	150	220		lm	I <sub>F</sub> =700mA	
Chromaticity Coordinates	Х	0.2740		0.3480		I <sub>F</sub> =700mA	
	Υ	0.2700		0.3850			
Colour Temperature	ССТ	5000	6300	10000	К	I <sub>F</sub> =700mA	
Viewing Angle	2θ <sub>1/2</sub>		120		deg	I <sub>F</sub> =700mA	

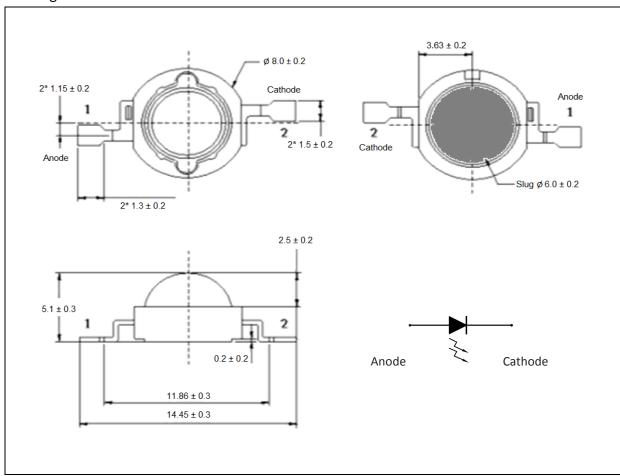
<sup>2.</sup> Luminous intensity (Iv) ±15%, Forward Voltage (VF) ±0.1V, Viewing angle(2 $\theta_{1/2}$ ) ±5%

<sup>3.</sup> IS standard testing



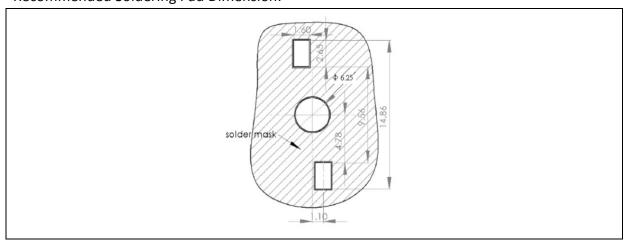
#### **OUTLINE DIMENSION:**

### Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm, unless otherwise noted.

#### Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



### **BINNING GROUPS:**

## Forward Voltage Classifications (I<sub>F</sub> = 700mA):

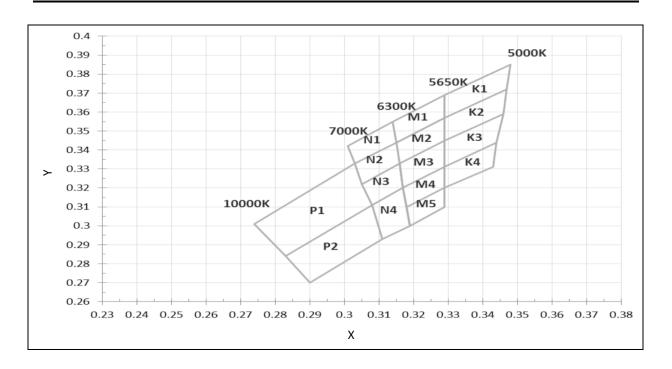
Code	Min.	Max.	Unit
1	2.8	2.9	
2	2.9	3.0	
3	3.0	3.1	
4	3.1	3.2	V
5	3.2	3.3	V
6	3.3	3.4	
7	3.4	3.5	
8	3.5	3.6	

## Luminous Flux Classifications (I<sub>F</sub> = 700mA):

Code	Min.	Max.	Unit
38	150	160	
39	160	170	
40	170	180	
41	180	190	
42	190	200	
43	200	210	lm
44	210	220	
45	220	230	
46	230	240	
47	240	250	
48	250	260	



#### **CIE CHROMATICITY DIAGRAM:**

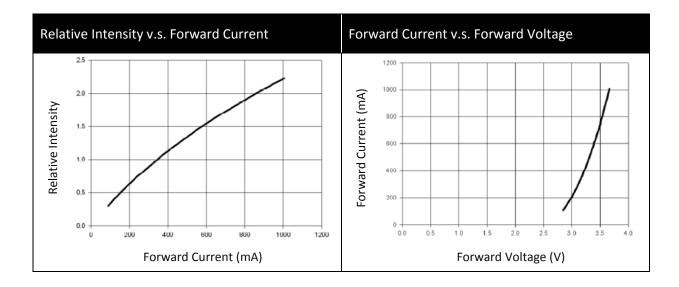


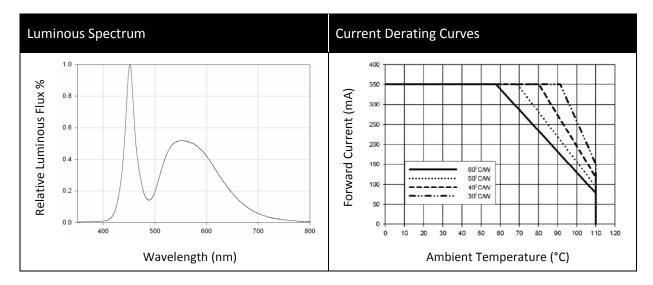
## Chromaticity Coordinates Classifications (IF = 700mA):

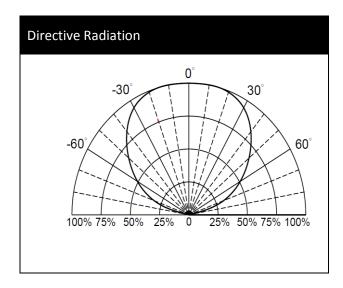
	1	1	2		3	3	4	
	Х	Υ	Х	Υ	Х	Υ	X	Υ
P1	0.3080	0.3110	0.2830	0.2840	0.2740	0.3010	0.3030	0.3330
P2	0.3080	0.3110	0.3110	0.2930	0.2900	0.2700	0.2830	0.2840
N1	0.3030	0.3330	0.3010	0.3420	0.3140	0.3550	0.3150	0.3440
N2	0.3050	0.3220	0.3030	0.3330	0.3150	0.3440	0.3160	0.3330
N3	0.3080	0.3110	0.3050	0.3220	0.3160	0.3330	0.3170	0.3200
N4	0.3080	0.3110	0.3170	0.3200	0.3190	0.3000	0.3110	0.2930
M1	0.3140	0.3550	0.3290	0.3690	0.3290	0.3570	0.3150	0.3440
M2	0.3150	0.3440	0.3290	0.3570	0.3290	0.3450	0.3160	0.3330
M3	0.3290	0.3450	0.3290	0.3310	0.3170	0.3200	0.3160	0.3330
M4	0.3290	0.3310	.03290	0.3200	0.3180	0.3100	0.3170	0.3200
M5	0.3290	0.3200	0.3290	0.3100	0.3190	0.3000	0.3180	0.3100
K1	0.3290	0.3570	0.3290	0.3690	0.3480	0.3850	0.3470	0.3720
K2	0.3290	0.3450	0.3290	0.3570	0.3470	0.3720	0.3460	0.3590
К3	0.3290	0.3310	0.3290	0.3450	0.3460	0.3590	0.3440	0.3440
К4	0.3290	0.3310	0.3440	0.3440	0.3430	0.3310	0.3290	0.3200



#### **ELECTRO-OPTICAL CHARACTERISTICS:**



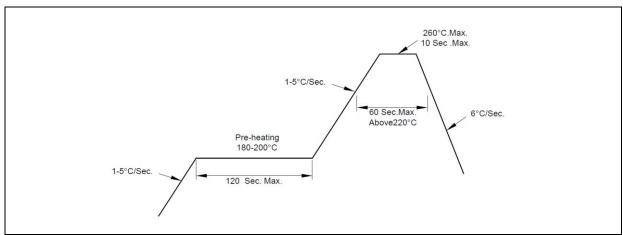






### **RECOMMENDED SOLDERING PROFILE:**

#### Lead-free Solder:



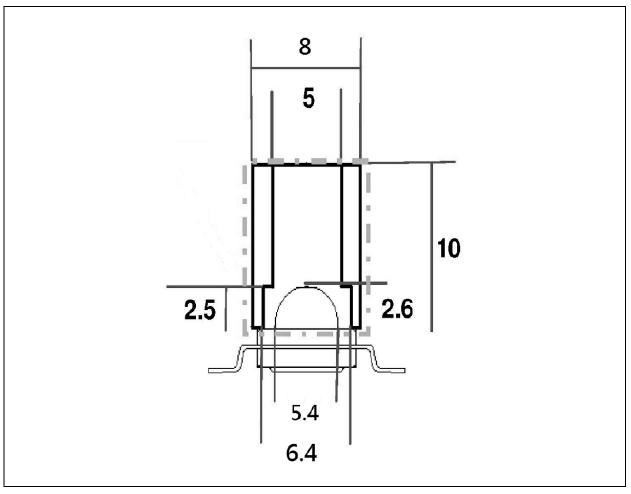
#### Note:

- 1. Maximum reflow soldering: 1 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



### **RECOMMENDED NOZZLE FOR SMT:**

#### Recommended Pick & Place Nozzle:

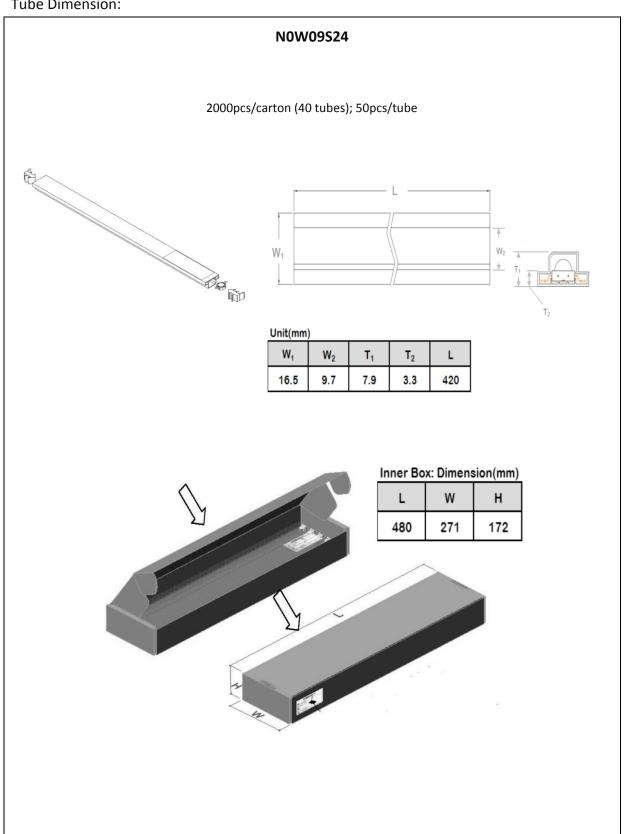


- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm, unless otherwise noted.



### **PACKING SPECIFICATION:**

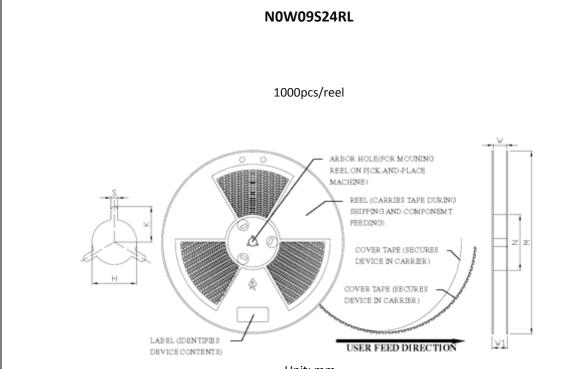
#### **Tube Dimension:**





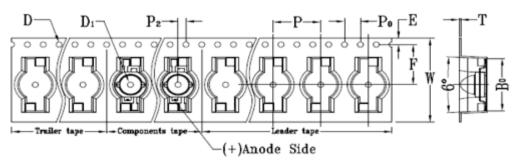
#### **PACKING SPECIFICATION:**

#### Reel Dimension:



Unit: mm

М	N	W	W1	H	K	S
Ф330.0	Ф99.5	24.4	29	Ф13.5	10.75	2.5
±1.0	±1.0	±1.0	±1.0	±0.5	±0.5	±0.5



Unit: mm

W	Р	E	F	P <sub>2</sub>	D	D <sub>1</sub>	P <sub>0</sub>	<b>A</b> <sub>0</sub>	B <sub>0</sub>	K <sub>0</sub>	Т
24.0	12.0	1.75	11.5	2.0	1.5	1.5	4.0	8.2	15.0	6.7	0.4
±0.3	±0.1	±0.1	±0.1	±0.1	±0.1	±0.25	±0.1	±0.1	±0.1	±0.1	±0.05



#### **PRECAUTIONS OF USE:**

#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

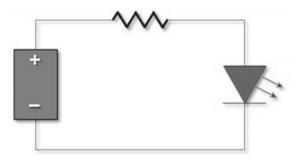
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.</li>
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

#### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

#### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

#### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



## **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	06/06/2014	Datasheet set-up.